

REVISIONS

LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Update drawing to current requirements. Editorial changes throughout. - drw	04-12-15	Raymond Monnin

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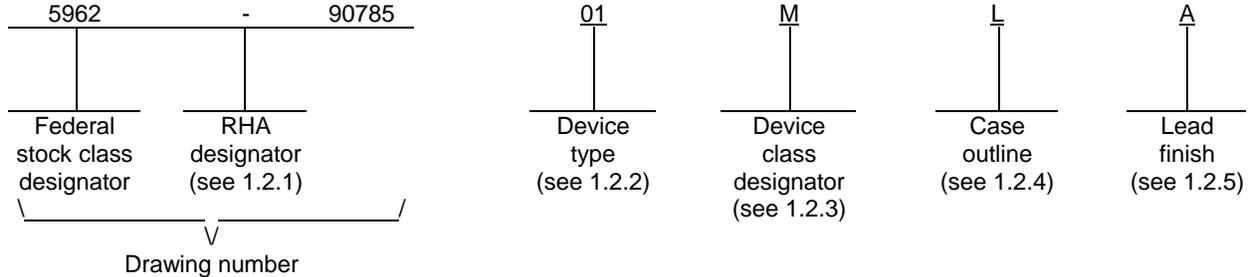
REV STATUS	REV	A	A	A	A	A	A	A	A	A	A	A	A	A	A		
OF SHEETS	SHEET	1	2	3	4	5	6	7	8	9	10	11	12				

PMIC N/A	PREPARED BY Dan Wonnell	DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990 http://www.dsccl.dla.mil															
STANDARD MICROCIRCUIT DRAWING THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE AMSC N/A	CHECKED BY Raymond Monnin																
	APPROVED BY Raymond Monnin	MICROCIRCUIT, DIGITAL-LINEAR, DUAL, 12-BIT D/A CONVERTERS, MONOLITHIC SILICON															
	DRAWING APPROVAL DATE 99-05-27																
	REVISION LEVEL A	SIZE A	CAGE CODE 67268	5962-90785													
		SHEET		1 OF 12													

1. SCOPE

1.1 Scope. This drawing documents two product assurance class levels consisting of high reliability (device classes Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels are reflected in the PIN.

1.2 PIN. The PIN is as shown in the following example:



1.2.1 RHA designator. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. Device class M RHA marked devices meet the MIL-PRF-38535, appendix A specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 Device types. The device types identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	AD7247A	Dual, CMOS, 12-bit D/A converters
02	AD7237A	Dual, CMOS, 12-bit D/A converters

1.2.3 Device class designator. The device class designator is a single letter identifying the product assurance level as follows:

<u>Device class</u>	<u>Device requirements documentation</u>
M	Vendor self-certification to the requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A
Q or V	Certification and qualification to MIL-PRF-38535

1.2.4 Case outline. The case outline is as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
L	GDIP3-T24 or CDIP4-T24	24	Dual-in-line

1.2.5 Lead finish. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

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1.3 Absolute maximum ratings.

V _{DD} to GND (device type 01)	-0.3 V to +17 V dc
V _{DD} to AGND, DGND (device type 02)	-0.3 V to +17 V dc
V _{DD} to V _{SS}	-0.3 V to +34 V dc
AGND to DGND (device type 02)	-0.3 V, V _{DD} +0.3V
V _{OUTA} , V _{OUTB} to AGND <u>1/</u>	V _{SS} - 0.3 V to V _{DD} + 0.3 V
REF OUT to AGND <u>1/</u>	0 V to V _{DD}
REF IN to AGND	-0.3 V to V _{DD} + 0.3 V
Digital inputs to DGND.....	-0.3 V to V _{DD} + 0.3 V
Storage temperature range.....	-65°C to +150°C
Lead temperature (soldering, 10 sec.).....	+300°C
Power dissipation to +75°C.....	1000 mW, derate above +75°C by 10 mW/°C
Thermal resistance, junction-to-ambient (θ _{JA}).....	120°C/W
Thermal resistance, junction-to-case (θ _{JC}).....	35°C/W

1.4 Recommended operating conditions.

Ambient operating temperature range (T_A)..... -55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.
 MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.
 MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <http://assist.daps.dla.mil/quicksearch/> or <http://assist.daps.dla.mil> or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

1/ The outputs may be shorted to voltages in this range provided the power dissipation of the package is not exceeded.

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3. REQUIREMENTS

3.1 Item requirements. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.

3.2.1 Case outline. The case outline shall be in accordance with 1.2.4 herein.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.3 Truth tables. The truth tables shall be as specified on figure 2.

3.3 Electrical performance characteristics and postirradiation parameter limits. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.

3.5 Marking. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.

3.5.1 Certification/compliance mark. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.

3.6 Certificate of compliance. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.

3.7 Certificate of conformance. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change for device class M. For device class M, notification to DSCC-VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change that affects this drawing.

3.9 Verification and review for device class M. For device class M, DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

3.10 Microcircuit group assignment for device class M. Device class M devices covered by this drawing shall be in microcircuit group number 56 (see MIL-PRF-38535, appendix A).

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TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions <u>1/</u> -55°C ≤ T _A ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Resolution	RES		1, 2, 3	All		12	Bits
Relative accuracy	RA	<u>2/</u>	1, 2, 3	All	-0.5	+0.5	LSB
Differential non-linearity	DNL	Must be monotonic <u>2/</u>	1, 2, 3	All	-0.9	+0.9	LSB
Unipolar offset error	UNI	DAC latch contents all 0's <u>3/</u>	1, 2, 3	All	-4.0	+4.0	LSB
Bipolar zero error	BZ _E	V _{DD} = 11.4 V, V _{SS} = -11.4 V and range = ±5 V V _{SS} = -15 V DAC latch contents 1000 0000 0000	1, 2, 3	All	-6.0	+6.0	LSB
Full scale error	A _E	<u>4/</u>	1, 2, 3	All	-6.0	+6.0	LSB
Reference output	REFOUT	<u>5/</u>	1, 2, 3	All	4.95	5.05	V
Reference temperature coefficient	REF TC	<u>6/</u>	1, 2, 3	All	-25	+25	PPM/°C
Reference load change	ΔREF	ΔREF OUT vs ΔI reference load current change (0 - 100 mA)	1, 2, 3	All		-1.0	mV
Reference input range	REF IN	<u>7/</u>	1, 2, 3	All	4.75	5.25	V
Reference input current	I _{IN}	REF IN = 5.0 V	1, 2, 3	All	-5.0	+5.0	μA
Digital input current (control inputs)	I _{INH}	V _{IN} = V _{DD}	1, 2, 3	All	-10	+10	μA
	I _{INL}	V _{IN} = 0				-150	
Digital input current (data inputs)	I _{IN}	V _{IN} = 0 V to V _{DD}	1, 2, 3	All	-10	+10	μA
Digital input high voltage	V _{INH}		1, 2, 3	All	2.4		V
Digital input low voltage	V _{INL}		1, 2, 3	All		0.8	V
Input capacitance	C _{IN}	see 4.4.1c	4	All		8	pF
Output range resistors	R _R		1, 2, 3	All	15	30	kΩ
Output voltage ranges	V _{OUT}	V _{SS} = 0 V (pin strappable)	1, 2, 3	All		+5	V
						+10	
		V _{SS} = -15 V (pin strappable)			-5	+5	
Power supply current	I _{DD}	Outputs unloaded	1, 2, 3	All		15	mA
	I _{SS}	Outputs unloaded (dual supplies)				+5	
Functional tests	FT	see 4.4.1d	7, 8	All			

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - continued.

Test	Symbol	Conditions ^{1/} -55°C ≤ T _A ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
$\overline{\text{CS}}$ to $\overline{\text{WR}}$ setup time	t ₁	see figure 3 ^{8/}	9, 10, 11	All	0		ns
$\overline{\text{CS}}$ to $\overline{\text{WR}}$ hold time	t ₂	see figure 3	9, 10, 11	All	0		ns
$\overline{\text{WR}}$ pulse width	t ₃	see figure 3	9, 10, 11	All	100		ns
Data valid to write setup time	t ₄	see figure 3	9, 10, 11	All	80		ns
Data valid to write setup time	t ₅	see figure 3	9, 10, 11	All	10		ns
Address to $\overline{\text{WR}}$ setup time	t ₆	see figure 3	9, 10, 11	02	0		ns
Address to $\overline{\text{WR}}$ hold time	t ₇	see figure 3	9, 10, 11	02	0		ns
$\overline{\text{LDAC}}$ pulse width	t ₈	see figure 3	9, 10, 11	02	100		ns

^{1/} V_{DD} = +12 V ±5% or +15 V ±15%, V_{SS} = 0 V or -12 V ±5% or -15 V ±5%, GND = 0 V, R_L = 2 kΩ, C_L = 100 pF. Parts are guaranteed over this supply range. Individual tests are performed using known worst case supply conditions.

^{2/} V_{DD} = +11.4 V, V_{SS} = -11.4 V and Range = ±5 V; V_{DD} = +14.25 V, V_{SS} = -14.25 V and range = +10 V; V_{DD} = +11.4 V, V_{SS} = 0 V and range = +5 V.

^{3/} V_{DD} = +14.25 V, V_{SS} = -14.25 V and Range = ±10 V; V_{DD} = +15.75 V, V_{SS} = 0 V and range = +10 V; V_{DD} = +11.4 V, V_{SS} = 0 V and range = +5 V; V_{DD} = +11.4 V, V_{SS} = -11.4 V and Range = ±5 V

^{4/} Measured with respect to REF IN and includes unipolar/bipolar offset error. V_{DD} = +11.4 V, V_{SS} = -11.4 V and Range = ±5 V; V_{DD} = +14.25 V, V_{SS} = -14.25 V and range = +10 V; V_{DD} = +15.75 V, V_{SS} = 0 V and range = +10 V; V_{DD} = +11.4 V, V_{SS} = 0 V and range = +5 V.

^{5/} Reference output voltage shall not change more than 0.39% from its original value, over the operating life of the device.

^{6/} If not tested, shall be guaranteed to the limits specified in table I.

^{7/} This is a recommended input range. Testing is done with nominal value of 5.0 V.

^{8/} All input signals are specified with t_R = t_F = 5 ns (10% to 90% of 5 V) and timed from a voltage level of 1.6 V.

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Device type	01	02
Case outline	L	
Terminal number	Terminal symbol	
1	REF OUT	REF INA
2	R _{OFSB}	REF OUT
3	V _{OUTB}	REF INB
4	DB11	R _{OFSB}
5	DB10	V _{OUTB}
6	GND	AGND
7	DB9	DB7
8	DB8	DB6
9	DB7	DB5
10	DB6	DB4
11	DB5	DB3
12	DB4	GND
13	DB3	DB2
14	DB2	DB1
15	DB1	DB0
16	DB0	A0
17	$\overline{\text{CSB}}$	A1
18	$\overline{\text{CSA}}$	$\overline{\text{CS}}$
19	$\overline{\text{WR}}$	$\overline{\text{WR}}$
20	V _{DD}	LDAC
21	V _{OUTA}	V _{DD}
22	V _{SS}	V _{OUTA}
23	R _{OFSA}	V _{SS}
24	REF IN	R _{OFSA}

FIGURE 1. Terminal connections.

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Device type 01

$\overline{\text{CSA}}$	$\overline{\text{CSB}}$	$\overline{\text{WR}}$	Function
X	X	1	No data transfer
1	1	X	No data transfer
0	1	0	DAC A latch transparent
1	0	0	DAC B latch transparent
0	0	0	Both DAC latches transparent

X = Don't care

Device type 02

$\overline{\text{CS}}$	$\overline{\text{WR}}$	A1	A0	$\overline{\text{LDAC}}$	Function
1	X	X	X	1	No data transfer
X	1	X	X	1	No data transfer
0	0	0	0	1	DAC A LS input latch transparent
0	0	0	1	1	DAC A MS input latch transparent
0	0	1	0	1	DAC B LS input latch transparent
0	0	1	1	1	DAC B MS input latch transparent
1	1	X	X	0	DAC A and DAC B latches updated simultaneously from the respective input latches

X = Don't care

FIGURE 2. Truth tables.

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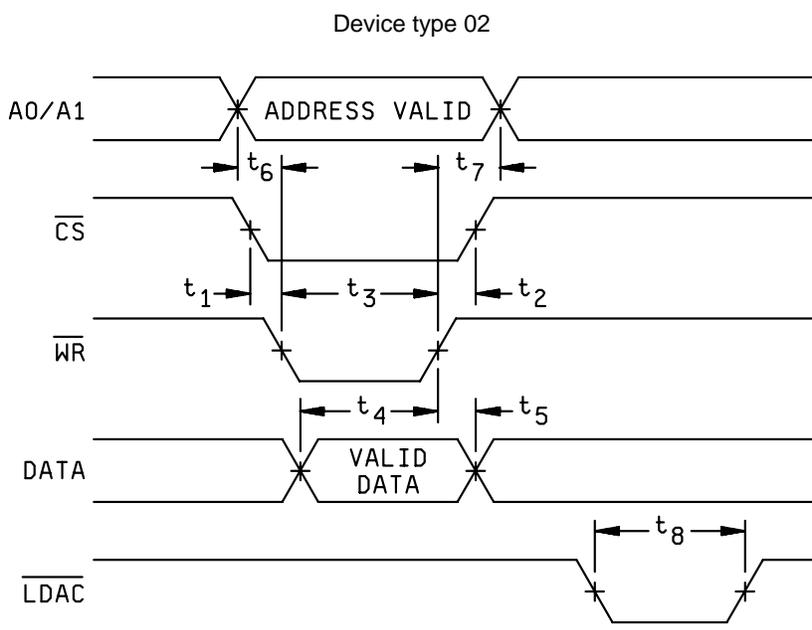
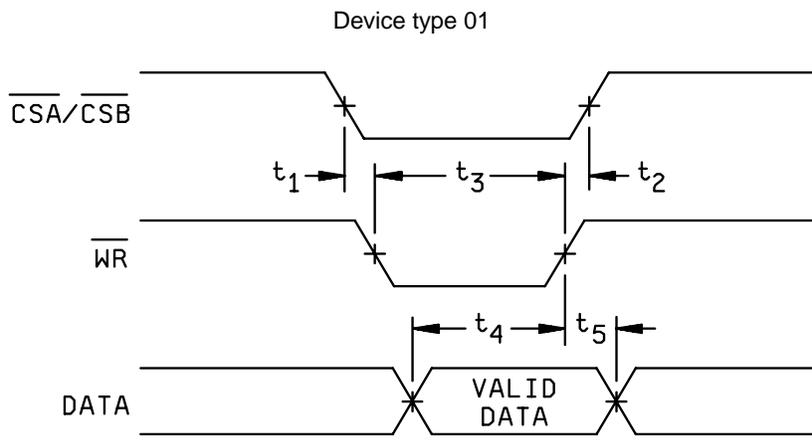


FIGURE 3. Timing waveforms.

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4. VERIFICATION

4.1 Sampling and inspection. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 Screening. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.

4.2.1 Additional criteria for device class M.

- a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015.
 - (2) $T_A = +125^{\circ}\text{C}$, minimum.
- b. Interim and final electrical test parameters shall be as specified in table II herein.

4.2.2 Additional criteria for device classes Q and V.

- a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
- b. Interim and final electrical test parameters shall be as specified in table II herein.
- c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

4.3 Qualification inspection for device classes Q and V. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 Conformance inspection. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified herein. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
- c. Subgroup 4 (C_{IN} measurement) shall be measured only for the initial test and after process or design changes which may affect input capacitance.
- d. For device class M, subgroups 7 and 8 tests shall be sufficient to verify the truth table. For device classes Q and V, subgroups 7 and 8 shall include verifying the functionality of the device.

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TABLE II. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)	Subgroups (in accordance with MIL-PRF-38535, table III)	
	Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)	1	1	1
Final electrical parameters (see 4.2)	1, 2, 3, <u>1/</u> 9, 10, 11	1, 2, 3, <u>1/</u> 9, 10, 11	1, 2, 3, <u>1/</u> 9, 10, 11
Group A test requirements (see 4.4)	1, 2, 3, 4, 7, 8, 9, 10, 11	1, 2, 3, 4, 7, 8, 9, 10, 11	1, 2, 3, 4, 7, 8, 9, 10, 11
Group C end-point electrical parameters (see 4.4)	1, 2, 3	1, 2, 3	1, 2, 3
Group D end-point electrical parameters (see 4.4)	1, 2, 3	1, 2, 3	1, 2, 3
Group E end-point electrical parameters (see 4.4)	----	----	----

1/ PDA applies to subgroup 1.

4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table II herein.

4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:

- a. Test condition A, B, C or D . The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
- b. $T_A = +125^{\circ}\text{C}$, minimum.
- c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table II herein.

4.4.4 Group E inspection. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).

- a. End-point electrical parameters shall be as specified in table II herein.
- b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535, appendix A for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at $T_A = +25^{\circ}\text{C} \pm 5^{\circ}\text{C}$, after exposure, to the subgroups specified in table II herein.

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5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor prepared specification or drawing.

6.1.2 Substitutability. Device class Q devices will replace device class M devices.

6.2 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.3 Record of users. Military and industrial users should inform Defense Supply Center Columbus (DSCC) when a system application requires configuration control and which SMD's are applicable to that system. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0544.

6.4 Comments. Comments on this drawing should be directed to DSCC-VA , Columbus, Ohio 43218-3990, or telephone (614) 692-0547.

6.5 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

6.6 Sources of supply.

6.6.1 Sources of supply for device classes Q and V. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DSCC-VA and have agreed to this drawing.

6.6.2 Approved sources of supply for device class M. Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

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STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 04-12-15

Approved sources of supply for SMD 5962-90785 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DSCC maintains an online database of all current sources of supply at <http://www.dscclia.mil/Programs/Smcr/>.

Standard microcircuit drawing PIN <u>1/</u>	Vendor CAGE number	Vendor similar PIN <u>2/</u>
5962-9078501MLA	24355	AD7247ATQ/883B
5962-9078502MLA	24355	AD7247ATQ/883B

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE
number

24355

Vendor name
and address

Analog Devices
Rt 1 Industrial Park
PO Box 9106
Norwood, MA 02062
Point of contact:

Raheen Business Park
Limerick, Ireland

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.